

ATTACHMENT - CLAIMS LISTING

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (withdrawn - currently amended) A method for stress measuring method changes in stress in a specimen, characterized by comprising the steps of:

irradiating a specimen with an electron beam when the specimen is in a predetermined state and when the specimen is in a state different from the predetermined state, said irradiating process that irradiates an electron beam on a of the specimen causing the specimen to generate light,

spectroscopically analyzing a spectroscopy process that analyses the light generated from the specimen by the above-mentioned electron-beam-irradiating step process and obtainings a spectrum for the specimen in the predetermined state and in the different state, and

a stress-calculating process that obtains a stress change in the specimen based on a spectrum shift of the spectrums obtained between a spectrum obtained from when the specimen is in a-the predetermined state and a spectrum obtained from when the specimen in a-state-the different from the predetermined state.

2. (withdrawn - currently amended) The method for stress measuring method described as claimed in claim 1, and characterized by that wherein a residual stress is obtained in the above-mentioned stress calculating process-step based on a spectrum shift between a specimen spectrum as being a spectrum in a state that no stress exists in the specimen and a stress impressed spectrum as being a spectrum in a state that a residual stress exists in the specimen.

3. (withdrawn - currently amended) The method for stress measuring method described as claimed in claim 1, wherein and characterized by that

an external force impressing process that applies an external force to the specimen prior to the above-mentioned electron beam irradiating process-step is further provided, and

an internal stress is obtained in the above-mentioned stress calculating process-step based on a spectrum shift between an internal stress impressed spectrum as being a spectrum in a state that an internal stress is generated in the specimen by the external force impressing process-step and a

specimen spectrum as being a spectrum in a state no stress exists in the specimen or a stress impressed spectrum as being a spectrum in a state that a residual stress exists in the specimen.

4. (withdrawn - currently amended) The method for stress measuring method described-as claimed in either one of claim 1 through claim 3, wherein and characterized by that

the above-mentioned-electron beam irradiating process-step includes a broad area electron beam irradiating process that irradiates an electron beam without narrowing down on a broad area that is broad enough compared with a spot size of the electron beam that is narrowed down to obtain a requested space resolution, and

in the stress calculating process-step a spectrum obtained by analyzing light generated from the specimen by the broad area electron beam irradiating process is made to be a specimen spectrum as being a spectrum in a state that no stress exists in the specimen.

5. (withdrawn - currently amended) The method for stress measuring method described-as claimed in either one of claim 1 through claim 3, wherein and characterized by that

the above-mentioned-electron beam irradiating process-step includes a broad area electron beam irradiating process that irradiates an electron beam on a broad area that is broad enough compared with a spot size of the electron beam that is narrowed down to obtain a requested space resolution with scanning the spot size, and

in the stress calculating process-step an average of spectra of light generated by irradiating each electron beam in the broad area electron beam irradiating step process-is made to be the specimen spectrum as being the spectrum in the state that no stress exists in the specimen.

6. (withdrawn - currently amended) The method for stress measuring method described-as claimed in claim 4, wherein the above-mentioned broad area is the entire area of the specimen.

7. (withdrawn - currently amended) The method for stress measuring method described-as claimed in claim 4, wherein a diameter of the above-mentioned broad area is set as not less than 100 times of the spot size of the electron beam that is narrowed down so as to obtain the required space resolution.

8. (withdrawn - currently amended) The method for stress measuring method described as claimed in claim 1, wherein and characterized by that

a minute amount sample obtaining process step that obtains a minute amount of a sample from the specimen is further included, and

in the stress calculating step process a spectrum of light obtained by irradiating an electron beam on the minute amount sample is made to be a specimen spectrum as being a spectrum in a state that no stress exists in the specimen.

9. (withdrawn - currently amended) The method for stress measuring method described as claimed in claim 1, wherein and characterized by that

a composition analyzing process that analyzes a partial difference of composition of the specimen is further included, and

in the above-mentioned stress calculating step process the above-mentioned specimen spectrum is determined for each area where composition of the specimen differs obtained by the above-mentioned composition analyzing step process in consideration of a spectrum shift generated due to the difference of composition.

10. (withdrawn - currently amended) The method for stress measuring method described as claimed in claim 1, wherein

external light whose spectrum is known is irradiated in the above-mentioned electron beam irradiating process,

a spectrum of the external light and a spectrum of light emission from the specimen are obtained in the above-mentioned spectroscopy process step, and

each position of spectra from the specimen in each state to be compared in order to measure a stress change is compensated based on the spectrum of the external light in the above-mentioned stress calculating process step.

11. (withdrawn - currently amended) The method for stress measuring method described as claimed in claim 10, wherein and characterized by that a position of a spectrum of a specimen

spectrum as being the spectrum in the state that no stress exists in the specimen and a position of a spectrum of the stress impressed spectrum as being a spectrum in a state that a residual stress exists in the specimen are compensated respectively based on a spectrum of external light in the above-mentioned stress calculating process step.

12. (withdrawn - currently amended) The method for stress measuring method described as claimed in claim 10, wherein characterized by that a position of a spectrum of an internal stress impressed spectrum as being a spectrum in a state that an internal stress exists in the specimen and a position of a spectrum of a specimen spectrum as being a spectrum in a state that no stress exists in the specimen or a position of a spectrum of the stress impressed spectrum as being a spectrum in a state that a residual stress exists in the specimen are compensated respectively based on a spectrum of external light in the above-mentioned stress calculating process step.

13. (withdrawn - currently amended) The method for stress measuring method described as claimed in claim 10, wherein a predetermined peak wavelength as being a reference for the above-mentioned external light spectrum is set near a predetermined peak wavelength for the light emission spectrum from the specimen.

14. (withdrawn - currently amended) The method for stress measuring method described as claimed in claim 1, wherein and characterized by that a correlation calculating process step that calculates a correlation between an amount of external force impressed on the specimen and an amount of the above-mentioned spectrum shift is included prior to the above-mentioned stress calculating process step.

15. (withdrawn - currently amended) The method for stress measuring method described as claimed in claim 1, wherein and characterized by that the above-mentioned specimen includes at least one kind of an element selected from a family consisting of lanthanoid by an amount within a range of 1 ppm ~ 10000 ppm.

16. (withdrawn - currently amended) The method for stress measuring method described as claimed in claim 15, wherein and characterized by that the above-mentioned lanthanoid is at least one element selected from a family consisting of Sm, Eu, Tb, Yb, La, Er, and Gd.

17. (currently amended) A stress measuring device characterized by comprising:
an electron beam irradiating unit that irradiates a specimen with an electron beam on a specimen,

a spectroscopy unit that analyzes light generated from the specimen by irradiation with the electron beam irradiating unit so as to obtain a spectrum of the generated light, and

a stress calculating unit that obtains calculates a stress change generated in the specimen based on a shift of the spectrum shift between a spectrum obtained when from the specimen is in a predetermined state and a spectrum obtained from when the specimen is in a state different from the predetermined state.

18. (currently amended) The stress measuring device described as claimed in claim 17, wherein and characterized by the above-mentioned stress calculating unit is to obtain a residual stress based on a spectrum shift between a specimen spectrum as being a spectrum in a state that no stress exists in the specimen and a stress impressed spectrum as being a spectrum in a state that a residual stress exists in the specimen.

19. (currently amended) The stress measuring device described as claimed in claim 17 characterized by that wherein an external force impressing unit that applies an external force to the specimen is further provided.

20. (currently amended) The stress measuring device described as claimed in claim 19, wherein and characterized by that the above-mentioned stress calculating unit is to obtain an internal stress from a spectrum shift between an internal stress impressed spectrum in a state that the internal stress is generated in the specimen by the external stress impressing unit and the above-mentioned specimen spectrum or the above-mentioned stress impressed spectrum.

21. (currently amended) The stress measuring device described as claimed in claim 17 characterized by that wherein a minute amount sample obtaining unit that obtains a minute amount of sample from the spectrum is further provided.

22. (currently amended) The stress measuring device described as claimed in claim 17 characterized by that wherein a composition analyzing unit that analyses a partial difference of composition of the specimen is further provided.

23. (currently amended) The stress measuring device described as claimed in claim 17 characterized by that wherein an external light irradiating unit that irradiates external light whose spectrum is known is further provided.

24. (currently amended) The stress measuring device described as claimed in claim 17 characterized by that wherein a visualizing unit that visualizes a portion to be measured of the above-mentioned specimen is further provided.

25. (currently amended) The stress measuring device described as claimed in claim 17 characterized by that wherein a diameter of a beam spot of an electron beam irradiated by the above-mentioned electron beam irradiating unit is not more than 100 nm.

26. (currently amended) The stress measuring device described as claimed in claim 17 characterized by that wherein the above-mentioned electron beam irradiating unit is a scanning electron microscope.

27. (currently amended) A stress measuring device characterized by comprising:
a light irradiating process-unit that irradiates a specimen with irradiating light on a specimen,
a spectroscopy process-unit that analyzes light generated from the specimen spectrum by the above-mentioned light-irradiating light process so as to obtain a spectrum of the generated light,
and

a stress calculating process-unit that obtains-calculates a stress change generated in the specimen based on a shift of the spectrum shift between a spectrum of the generated light obtained from-when the specimen is in a predetermined state and a spectrum obtained from-when the specimen is in a state different from the predetermined state,

wherein the light irradiating process-unit includes a broad area light irradiating process device that irradiates the irradiating light without narrowing down the irradiating light on a broad area that is broad enough-compared with a smaller spot size of the irradiating light that is narrowed down to obtain a requested space resolution, and

wherein in the above-mentioned stress calculating process-unit, a spectrum obtained by analyzing light generated from the specimen by the broad area light-irradiating light process is made to be a specimen-the spectrum as being a spectrum in a-the predetermined state that-where no stress exists in the specimen.

28. (currently amended) The A stress measuring device characterized by comprising:
a light irradiating process-unit that irradiates a specimen with irradiating light-on a specimen,
a spectroscopy process-unit that analyzes light generated from the specimen spectrum-by the above-mentioned light-irradiating light process-unit so as to obtain spectrum of the generated light, and

a stress calculating process-unit that obtains-calculates a stress change generated in the specimen based on a shift of the spectrum shift between a spectrum of the generated light obtained from-when the specimen is in a predetermined state and a spectrum obtained from-when the specimen is in a state different from the predetermined state,

wherein the above-mentioned-light irradiating process-unit includes a broad area light irradiating process-device that irradiates the irradiating light on a broad area that is broad enough compared with a smaller spot size of the irradiating light that is narrowed down to obtain a requested space resolution with scanning of the smaller spot-size, and

wherein in the above-mentioned stress calculating process-unit, an average of spectra of the light-generated by-irradiating each irradiating light in the broad area light irradiating process is made to be a specimen-the spectrum as being a spectrum in a-the predetermined state that-where no stress exists in the specimen.

29. (withdrawn - currently amended) A method of measuring stress comprising the steps of:
providing a specimen to be measured;
irradiating the specimen with an electron beam;
measuring the-radiation from the specimen after contactirradiation with the electron beams;
and

calculating thea stress on the specimen based upon a spectrum shift between a first spectrum
of the radiation when the specimen is in a predetermined reference state and a second spectrum
of the radiation measured at a predetermined measurement position on the specimen.

30. (withdrawn - currently amended) The method as claimed in of claim 29 wherein the first
spectrum of the predetermined reference state is determined by averaging a plurality of
measurements across the specimen to approximate a stress-free state for the specimen.

31. (withdrawn - currently amended) The method ofas claimed in claim 30 wherein the
plurality of measurements represents an area of the specimen which is approximately 100 times
as large or larger than the predetermined measurement position.

32. (withdrawn - currently amended) The method ofas claimed in claim 29 wherein the
predetermined reference state is determined by measuring the first spectrum while exerting a
stress force on the specimen of a predetermined value and the second spectrum at the
predetermined measurement position is measured without exerting the stress force.

33. (withdrawn - currently amended) The method ofas claimed in claim 32 wherein the stress
force is applied mechanically to the specimen.

34. (withdrawn - currently amended) The method ofas claimed in claim 32 wherein the stress
force is applied thermally to the specimen.

35. (withdrawn - currently amended) The method of as claimed in claim 32 wherein the predetermined reference state is measured over a plurality of different stress forces to correlate the amount of external force and the corresponding spectrum shift.

36. (withdrawn - currently amended) The method of as claimed in claim 29 further including preparing the specimen to be measured by including within the specimen a predetermined material that can be activated by the electron beam to emitting radiation.

37. (withdrawn - currently amended) The method of as claimed in claim 35 wherein the predetermined material includes at least one element from a lanthanoid series of elements.

38. (withdrawn - currently amended) The method of as claimed in claim 36 wherein the ratio of the lanthanoid to the specimen is within a range of 1 ppm to approximately 10000 ppm.

39. (withdrawn - currently amended) The method of as claimed in claim 29 further including determining the composition of the specimen and adjusting the calculate stress on the basis of the determined composition relative to a predetermined composition standard for the specimen.

40. (withdrawn - currently amended) The method of as claimed in claim 29 further including controlling the temperature of the specimen during the measurement steps to a predetermined temperature.

41. (withdrawn - currently amended) The method of as claimed in claim 29 further including irradiating the specimen with a predetermined light radiation and measuring the radiation from the specimen after contact with the light radiation to provide a peak reference for compensation of the electron beam calculated stress.

42. (withdrawn - currently amended) The method of as claimed in claim 29 wherein the predetermined measurement position is irradiated by an electron beam having a diameter of 10 nm or less.

43. (withdrawn - currently amended) The method of as claimed in claim 29 further including measuring the residual stress in the specimen by measuring at least a portion of the specimen in a state without any residual stress and calculating peak shifts of the first and second spectrums.

44. (currently amended) A system for measuring stress in a specimen with an electron beam comprising:

a irradiating unit for providing an electron beam to irradiate the specimen;

a measuring unit for providing measurement signals of the radiation from the specimen after ~~contact~~irradiation with the electron beams; and

a calculating unit for calculating the stress on the specimen from the measurement signals by determining a spectrum shift between a first spectrum of the radiation when the specimen is in a predetermined reference state and a second spectrum of the radiation measured at a predetermined measurement position on the specimen.

45. (currently amended) The system of as claimed claim 44 wherein the first spectrum of the predetermined reference state is determined by the calculating unit by averaging a plurality of measurements across the specimen to approximate a stress-free state for the specimen.

46. (currently amended) The system of as claimed claim 45 wherein the irradiating unit directs the electron beam to enable a plurality of measurements representative of an area of the specimen which is approximately 100 times as large or larger than the predetermined measurement position.

47. (currently amended) The system of as claimed claim 44 further including a stress force applying unit wherein the predetermined reference state is determined by measuring the first spectrum while exerting a stress force on the specimen of a predetermined value and the second spectrum at the predetermined measurement position is measured without exerting the stress force.

48. (currently amended) The system ~~of as claimed~~ claim 47 wherein the stress force is applied mechanically to the specimen.

49. (currently amended) The system ~~of as claimed~~ claim 47 wherein the stress force is applied thermally to the specimen.

50. (currently amended) The system ~~of as claimed~~ claim 47 wherein the predetermined reference state is measured over a plurality of different stress forces to correlate the amount of external force and the corresponding spectrum shift.

51. (currently amended) The system ~~of as claimed~~ claim 44 further including a doping unit for preparing wherein the specimen to be measured by including within the specimen includes a predetermined material that can be activated by the electron beam to emitting radiation.

52. (currently amended) The system ~~of as claimed~~ claim 51 wherein the predetermined material includes at least one element from a lanthanoid series of elements.

53. (currently amended) The system ~~of as claimed~~ claim 52 wherein the ratio of the lanthanoid element to the specimen is within a range of 1 ppm to approximately 10000 ppm.

54. (currently amended) The system ~~of as claimed~~ claim 44 further including a composition analyzing unit for determining the composition of the specimen and adjusting the calculate stress on the basis of the determined composition relative to a predetermined composition standard for the specimen.

55. (currently amended) The system ~~of as claimed~~ claim 44 further including a temperature control unit for controlling the temperature of the specimen during the measurement to a predetermined temperature.

56. (currently amended) The system ~~ef-as claimed~~ claim 44 further including a light radiating unit for illuminating the specimen with light and a light measuring unit for measuring radiation from the specimen after contact with the light radiation to provide a peak reference for compensation of the electron beam calculated stress.

57. (currently amended) The system ~~ef-as claimed~~ claim 44 wherein the predetermined measurement position is irradiated by an electron beam having a diameter of 10 nm or less from the irradiating unit.